

Solid Tantalum Chip Capacitors MICROTANTM Leadframeless Molded





FEATURES

- Small sizes include 0603 and 0402 footprint
- Lead (Pb)-free L-shaped terminations
- 8 mm tape and reel packaging available per EIA-481-1 and reeling per IEC 286-3 7" [178 mm] standard







PERFORMANCE CHARACTERISTICS

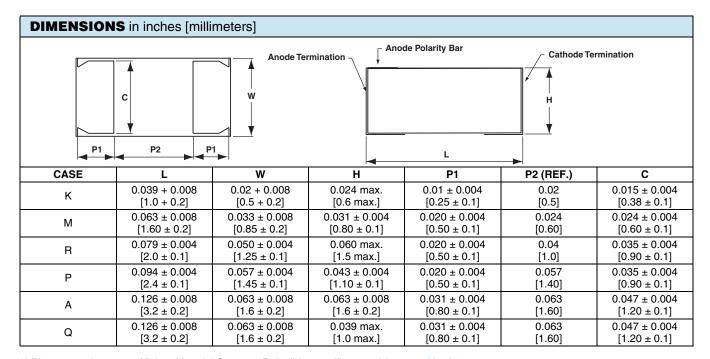
Operating Temperature: - 55 °C to + 85 °C (to + 125 °C voltage derating)

Capacitance Range: 1 μF to 220 μF
Capacitance Tolerance: ± 20 % standard
Voltage Range: 2.5 WV_{DC} to 50 WV_{DC}

ORDE	ORDERING INFORMATION							
298D	106	Х0	010	M	2	T		
MODEL	CAPACITANCE	CAPACITANCE	DC VOLTAGE RATING	CASE CODE	TERMINATION	REEL SIZE AND		
		TOLERANCE I	AT + 85 °C			PACKAGING		
	This is expressed in picofarads. The first two digits are the significant figures. The third is the number of zeros to follow.	X0 = ± 20 % X9 = ± 10 %	This is expressed in volts. To complete the three-digit block, zeros precede the voltage rating. A decimal point is indicated by an "R" (6R3 = 6.3 V).	See Ratings and Case Codes table	2 = 100 % tin 4 = Gold plated	T = Tape and reel 7" [178 mm] reel		

Note

Preferred tolerance and reel size are in bold.
 We reserve the right to supply higher voltage ratings and tighter capacitance tolerance capacitors in the same case size.
 Voltage substitutions will be marked with the higher voltage rating



^{**} Please see document "Vishay Material Category Policy" (5-2008)": www.vishay.com/doc?99902



Vishay Sprague

RATING	RATINGS AND CASE CODES								
μF	2.5 V	4 V	6.3 V	10 V	16 V	20 V	25 V	35 V	50 V
1.0			K	K	K/M		M/R		Р
1.5				М					
2.2			K/M	K/M	М				
3.3			M	М					
4.7		K	K*/M	М	М	Р	Р		
6.8									
10		K/M	K*/M	М	R				
15		K	M	М					
22		М	M	М					
33		М	М	Р					
47	М	М	Р	Р					
100		Р	P/A/Q*						
220	Р	Р							

Note
* Preliminary values, contact factory for availability.

	VOLTAG	E CODE	CAPACITA	NCE CODE	
	V	CODE	CAP, µF	CODE	P, R-Case
M-Case	2.5	е	0.68	w	Voltage Capacitance Polarity Bar Code Code
Polarity Bar Voltage Code	4	G	1	Α	, 5,000
	6.3	J	2.2	J	
	10	Α	3.3	N	$G\overline{J}$
A	16	С	4.7	S	GJ
	20	D	6.8	W	
	25	Е	10	α	
K-Case	35	V	15	е	Voltage EIA Capacit Polarity Bar Code Code (pF)
K-Case	50	T	22	j	Polarity Bar Code Code (pF)
			33	n	
			47	S	
			68	w	J107
			100	Ā	0.107
			150	Ē	
			220	J	

STANDARI	RATII	NGS							
CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DC LEAKAGE AT + 25 °C (μA)	MAX. DF AT + 25 °C (%)	MAX. ESR AT + 25 °C 100 kHz (Ω)	MAX. RIPPLE 100 kHz I _{rms} (A)	Δ C/C ⁽¹⁾ (%)		
		2.5 WV _{DC}	AT + 85 °C,	1.6 WV _{DC} AT +	125 °C				
47	М	298D476X02R5M2T	2.4	20	4.0	0.080	± 30		
220	Р	298D227X02R5P2T	11.0	30	3.0	0.122	± 30		
	4 WV _{DC} AT + 85 °C, 2.7 WV _{DC} AT + 125 °C								
4.7	K	298D475X0004K2T	0.5	15.0	20.0	0.027	± 30		
10	K	298D106X0004K2T	4.0	50.0	20.0	0.027	± 30		
10	M	298D106X0004M2T	0.5	8.0	5.0	0.071	± 10		
15	K	298D156X0004K2T	10.0	50.0	20.0	0.027	± 30		
22	M	298D226X0004M2T	0.9	15.0	4.0	0.080	± 15		
33	M	298D336X0004M2T	2.6	30.0	4.0	0.080	± 20		
47	M	298D476X0004M2T	3.8	40.0	7.5	0.080	± 30		
100	Р	298D107X0004P2T	4.0	30.0	2.0	0.100	± 30		
220	Р	298D227X0004P2T (3)	17.6	30.0	3.0	0.122	± 30		

Solid Tantalum Chip Capacitors MICROTANTM Leadframeless Molded



CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DC LEAKAGE AT + 25 °C (μA)	MAX. DF AT + 25 °C (%)	MAX. ESR AT + 25 °C 100 kHz (Ω)	MAX. RIPPLE 100 kHz I _{rms} (A)	∆C/C ⁽¹⁾ (%)
		6.3 WV _{DC}	C AT + 85 °C,	. 4 WVpc AT + 1		(1-)	
1.0	K	298D105X06R3K2T	0.5	6.0	20.0	0.027	± 30
2.2	K	298D225X06R3K2T	0.5	8.0	20.0	0.027	± 30
2.2	М	298D225X06R3M2T (3)	0.5	10.0	5.0	0.070	± 10
3.3	М	298D335X06R3M2T (3)	0.5	8.0	6.0	0.090	
4.7	K	298D475X06R3K2T (2)	4.0	50.0	20.0	0.027	± 30
4.7	М	298D475X06R3M2T (2)	0.5	8.0	3.0	0.090	± 10
10	K	298D106X06R3K2T (2)	10.0	50.0	20.0	0.027	± 30
10	М	298D106X06R3M2T (3)	0.6	8.0	5.0	0.071	± 10
15	М	298D156X06R3M2T (3)	1.0	20.0	7.0	0.060	± 20
22	М	298D226X06R3M2T	2.8	20.0	5.5	0.067	± 15
33	М	298D336X06R3M2T	4.2	30.0	7.5	0.058	± 30
47	Р	298D476X06R3P2T	3.0	22.0	3.0	0.122	± 20
100	Α	298D107X06R3A2T	6.3	20.0	1.0	0.270	± 10
100	Q	298D107X06R3Q2T (2)	63.0	30.0	1.1	0.220	± 20
100	Р	298D107X06R3P2T	6.3	30.0	2.0	0.150	± 20
		10 WV _{DC}	AT + 85 °C,	7 WV _{DC} AT + 1	25 °C		
1.0	K	298D105X0010K2T	0.5	6.0	20.0	0.027	± 30
1.5	M	298D155X0010M2T (3)	0.5	6.0	14.0	0.040	
2.2	K	298D225X0010K2T	0.5	8.0	15.0	0.027	± 30
2.2	М	298D225X0010M2T	0.5	10.0	10.0	0.050	± 10
3.3	M	298D335X0010M2T (3)	0.5	8.0	6.0	0.090	
4.7	M	298D475X0010M2T (3)	0.5	6.0	5.0	0.071	± 15
10	M	298D106X0010M2T	1.0	20.0	7.5	0.058	± 15
15	М	298D156X0010M2T (3)	1.5	30.0	7.5	0.058	± 20
22	М	298D226X0010M2T	22.0	40.0	10.0	0.050	± 30
33	Р	298D336X0010P2T (3)	3.3	20.0	4.0	0.150	± 10
47	Р	298D476X0010P2T	4.7	22.0	3.0	0.122	± 20
		16 WV _{DC}	AT + 85 °C,	10 WV _{DC} AT + 1	125 °C		
1.0	K	298D105X0016K2T	3.0	10.0	20.0	0.027	± 30
1.0	М	298D105X0016M2T (3)	0.5	6.0	12.0	0.045	± 15
2.2	M	298D225X0016M2T (3)	0.5	10.0	12.0	0.045	± 15
4.7	М	298D475X0016M2T	0.8	8.0	6.0	0.060	± 15
10	R	298D106X0016R2T	1.6	8.0	8.0	0.075	± 10
			AT + 85 °C,	13 WV _{DC} AT + 1	125 °C		
4.7	Р	298D475X0020P2T (3)	1.0	6.0	4.0	0.106	± 10
			AT + 85 °C,				
1.0	M	298D105X0025M2T	0.5	6.0	10.0	0.050	± 10
1.0	R	298D105X0025R2T	0.5	6.0	10.0	0.050	± 10
4.7	P	298D475X0025P2T ⁽³⁾	1.2	6.0	4.0	0.106	± 10
10	Α	298D106X0025A2T (2)(3)	2.5	10.0	3.5	0.146	± 10
			AT + 85 °C,				
1.0	Р	298D105X0050P2T	0.5	8.0	8.0	0.075	± 10

Notes

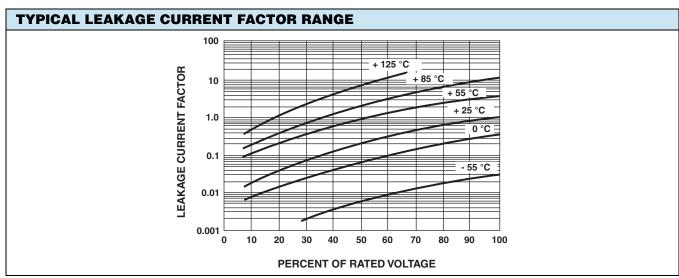
⁽¹⁾ See Performance Characteristics tables (2) In development

 $^{^{(3)}}$ ± 10 % capacitance tolerance available

Vishay Sprague

CAPACITORS PERFORMANCE CHARACTERISTICS

ITEM	PERFORMANCE CHARACTERISTICS					
Category Temperature Range	- 55 °C to + 85 °C (to + 12	25 °C with voltage deratin	g)			
Capacitance Tolerance	± 20 %, ± 10 % (at 120 H	z) 2 V _{RMS} at + 25 °C usin	g a capacitance bridge			
Dissipation Factor (at 120 Hz)			je method, at 25 °C, 120 Hz			
ESR (100 kHz)	Limits per Standard Ratin	gs Table. Tested via bridg	ge method, at 25 °C, 100 kH	Z.		
Leakage Current	with 1 $k\Omega$ resistor in seried described in Standard R	After application of rated voltage applied to capacitors for 5 minutes using a steady source of power with 1 $k\Omega$ resistor in series with the capacitor under test, leakage current at 25 °C is not more than described in Standard Ratings Table. Note that the leakage current varies with temperature and applied voltage. See graph below for the appropriate adjustment factor.				
Reverse Voltage	rating at + 25 °C 5 % of the DC rating at +	Capacitors are capable of withstanding peak voltages in the reverse direction equal to: 10 % of the DC				
Temperature Derating	If capacitors are to be used at temperatures above + 25 °C, the permissible rms ripple current or voltage shall be calculated using the derating factors: 1.0 at + 25 °C 0.9 at + 85 °C 0.4 at + 125 °C					
	+ 85 °C R	RATING	+ 125 °C I	+ 125 °C RATING		
	WORKING VOLTAGE (V)	SURGE VOLTAGE (V)	WORKING VOLTAGE (V)	SURGE VOLTAGE (V)		
	4	5.2	2.7	3.4		
	6.3	8	4	5		
Operating Temperature	10	13	7	8		
Operating remperature	16	20	10	12		
	20	26	13	16		
	25	32	17	20		
	35	46	23	28		
	50	65	33	40		



Notes

- At + 25 °C, the leakage current shall not exceed the value listed in the Standard Ratings table
- At + 85 °C, the leakage current shall not exceed 10 times the value listed in the Standard Ratings table
- At + 125 °C, the leakage current shall not exceed 12 times the value listed in the Standard Ratings table

Solid Tantalum Chip Capacitors MICROTANTM Leadframeless Molded



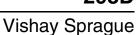
ENVIRONMENTAL PERFORMANCE CHARACTERISTICS						
ITEM	CONDITION	POST TEST PERFORMANCE				
Life Test at + 85 °C	1000 h application of rated voltage at 85 °C with a 3 Ω series resistance, MIL-STD-202G method 108A	Capacitance change Dissipation factor Leakage current	Refer to Standard Ratings table Not to exceed 150 % of initial Not to exceed 200 % of initial			
Humidity Tests	At 40 °C/90 % RH 500 h, no voltage applied. MIL-STD-202G method 103B	Capacitance change Dissipation factor Leakage current	Refer to Standard Ratings table Not to exceed 150 % of initial Not to exceed 200 % of initial			
Thermal Shock	At - 55 °C/+ 125 °C, 30 min each, for 5 cycles. MIL-STD-202G method 107G	Capacitance change Dissipation factor Leakage current	Refer to Standard Ratings table Not to exceed 150 % of initial Not to exceed 200 % of initial			

TEST CONDITION	CONDITION	POST TEST PERFORMANCE		
Terminal Strength	Apply a pressure load of 5 N for 10 s ± 1 s horizontally to the center of capacitor side body.	Capacitance change Refer to Standard Ratings table Dissipation factor Initial specified value or less Leakage current Initial specified value or less		
	AEC Q-200 rev. C method 006	There shall be no mechanical or visual damage to capacitor post-conditioning.		
Substrate Bending (Board flex)	With parts soldered onto substrate test board, apply force to the test board for a deflection of 1 mm. AEC-Q200 rev. C method 005	Capacitance change Refer to Standard Ratings table Dissipation factor Initial specified value or less Leakage current Initial specified value or less		
Vibration	MIL-STD-202G, method 204D, 10 Hz to 2000 Hz, 20 <i>g</i> peak	Capacitance change Refer to Standard Ratings table Dissipation factor Initial specified value or less Leakage current Initial specified value or less		
		There shall be no mechanical or visual damage to capacitors post-conditioning.		
Shock	MIL-STD-202G, method 213B, Condition I, 100 g peak	Capacitance change		
	100 g peak	There shall be no mechanical or visual damage to capacitors post-conditioning.		
Resistance to Solder Heat	At 260 °C, for 10 s, reflow	Capacitance change Dissipation factor Leakage current Refer to Standard Ratings table Not to exceed 150 % of initial Not to exceed 200 % of initial		
		There shall be no mechanical or visual damage to capacitor post-conditioning.		
Solderability	MIL-STD-202G, method 208H, ANSI/J-STD-002, Test B. Applies only to solder and tin plated terminations. Does not apply to gold terminations.	There shall be no mechanical or visual damage to capacitor post-conditioning.		
Resistance to Solvents	MIL-STD-202, method 215D	There shall be no mechanical or visual damage to capacitor post-conditioning.		
Flammability	Encapsulation materials meet UL 94 V-0 with an oxygen index of 32 %.			

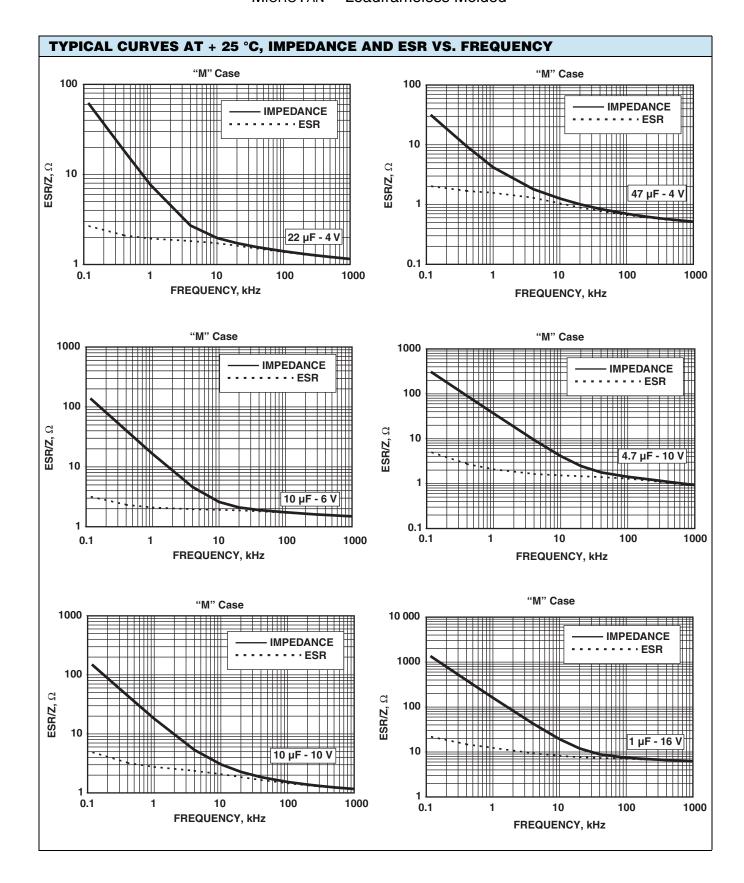
Downloaded from Elcodis.com electronic components distributor

Revision: 15-Jan-11

Document Number: 40065

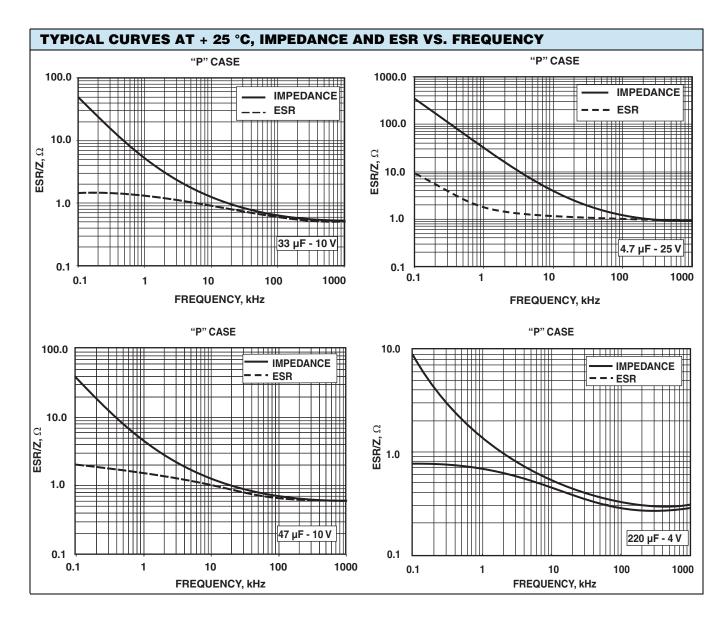






Solid Tantalum Chip Capacitors MICROTANTM Leadframeless Molded

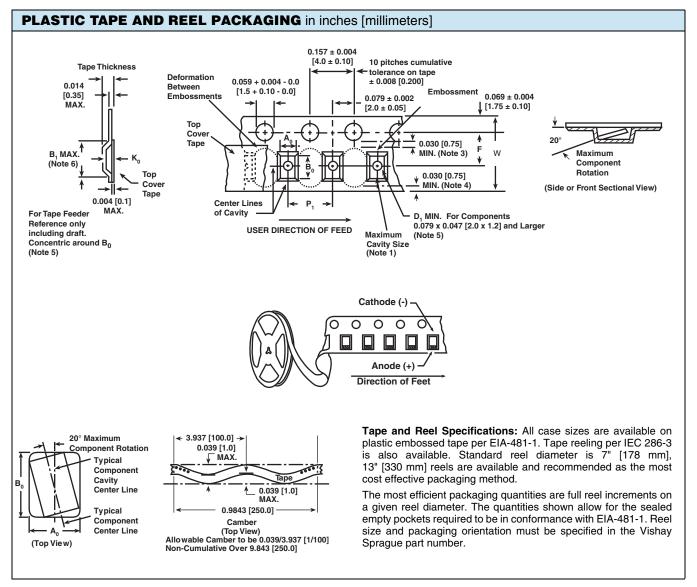




Document Number: 40065



Vishay Sprague



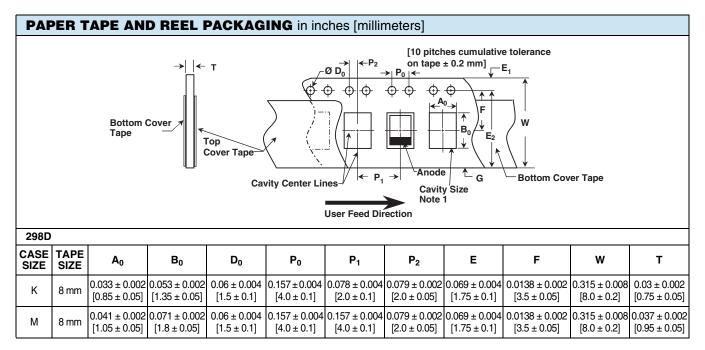
Note

• Metric dimensions will govern. Dimensions in inches are rounded and for reference only.

CASE CODE	TAPE SIZE	B ₁ (MAX.)	D ₁ (MIN.)	F	K ₀ (MAX.)	P ₁	w
298D							
P, R	8 mm	0.108 [2.75]	0.039 [1.0]	0.138 ± 0.002 [3.5 ± 0.05]	0.054 [1.37]	0.157 ± 0.004 [4.0 ± 1.0]	0.315 ± 0.0118/- 0.0039 [8.0 ± 0.30/- 0.10]
А	8 mm	0.165 [4.2]	0.039 [1.0]	0.138 ± 0.002 [3.5 ± 0.05]	0.094 [2.4]	0.157 ± 0.004 [4.0 ± 1.0]	0.315 ± 0.012 [8.0 ± 0.30]

Solid Tantalum Chip Capacitors MICROTANTM Leadframeless Molded





STANDARD PACKAGING QUANTITY						
SERIES	CASE CODE	QUANTITY (PCS/REEL)				
SERIES	CASE CODE	7" REEL				
	К	5000				
	M	4000				
298D	Р	3000				
	R	2500				
	A	2000				

RECOMMENDED VOLTAGE DERATING GUIDELINES					
STANDARD CONDITIONS: FOR EXAMPLE: OUTPUT FILTERS					
Capacitor Voltage Rating	Operating Voltage				
4.0	2.5				
6.3	3.6				
10	6.0				
16	10				
20	12				
25	15				
35	24				
50	28				
SEVERE CONDITIONS: FOR EXAMPLE: INPUT FILTERS					
Capacitor Voltage Rating	Operating Voltage				
4.0	2.5				
6.3	3.3				
10	5.0				
16	8.0				
20	10				
25	12				
35	15				
50	24				

www.vishay.com

For technical questions, contact: tantalum@vishay.com

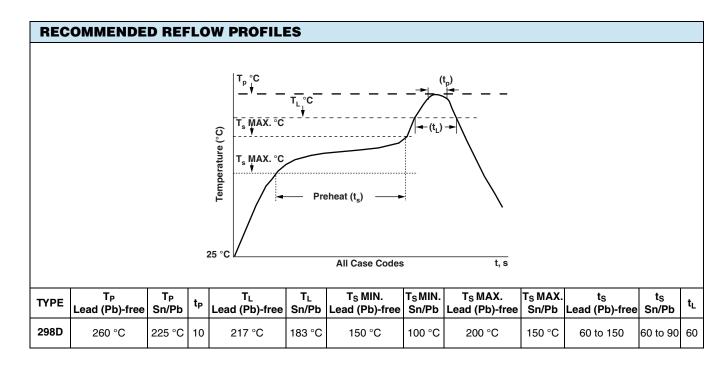
Revision: 15-Jan-11

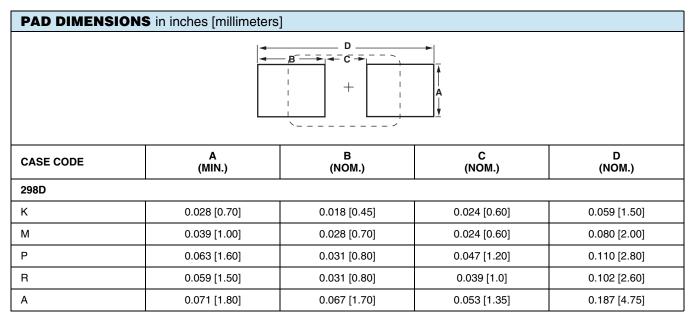
Document Number: 40065



Vishay Sprague

POWER DISSIPATION					
CASE CODE		MAXIMUM PERMISSIBLE POWER DISSIPATION AT + 25 °C (W) IN FREE AIR			
	К	0.015			
	М	0.025			
298D	Р	0.045			
	R	0.045			
	Α	0.075			





Solid Tantalum Chip Capacitors MICROTANTM Leadframeless Molded



GUIDE TO APPLICATION

 A-C Ripple Current: The maximum allowable ripple current shall be determined from the formula:

$$I_{rms} = \sqrt{\frac{P}{R_{FSR}}}$$

where,

P = Power dissipation in Watts at + 25 °C as

given in the table in paragraph number 5

(power dissipation).

R_{ESR} = The capacitor equivalent series resistance

at the specified frequency.

2. **A-C Ripple Voltage:** The maximum allowable ripple voltage shall be determined from the formula:

$$V_{rms} = Z \sqrt{\frac{P}{R_{ESR}}}$$

or, from the formula:

$$V_{rms} = I_{rms} \times Z$$

where,

P = Power dissipation in Watts at + 25 °C as

given in the table in paragraph number 5

(power dissipation).

R_{ESR} = The capacitor equivalent series resistance

at the specified frequency.

Z = The capacitor impedance at the specified

frequency.

- 2.1 The sum of the peak AC voltage plus the applied DC voltage shall not exceed the DC voltage rating of the capacitor.
- 2.2 The sum of the negative peak AC voltage plus the applied DC voltage shall not allow a voltage reversal exceeding 10 % of the DC working voltage at + 25 °C.
- Reverse Voltage: These capacitors are capable of withstanding peak voltages in the reverse direction equal to 10 % of the DC rating at + 25 °C, 5 % of the DC rating at + 85 °C and 1 % of the DC rating at + 125 °C.
- 4. **Temperature Derating:** If these capacitors are to be operated at temperatures above + 25 °C, the permissible rms ripple current or voltage shall be calculated using the derating factors as shown:

TEMPERATURE	DERATING FACTOR
+ 25 °C	1.0
+ 85 °C	0.9
+ 125 °C	0.4

5. Power Dissipation: Power dissipation will be affected by the heat sinking capability of the mounting surface. Non-sinusoidal ripple current may produce heating effects which differ from those shown. It is important that the equivalent I_{rms} value be established when calculating permissible operating levels. (Power Dissipation calculated using + 25 °C temperature rise.)

- 6. **Printed Circuit Board Materials:** Molded capacitors are compatible with commonly used printed circuit board materials (alumina substrates, FR4, FR5, G10, PTFE-fluorocarbon and porcelanized steel).
- 7. Attachment:
- 7.1 **Solder Paste:** The recommended thickness of the solder paste after application is 0.007" ± 0.001" [0.178 mm ± 0.025 mm]. Care should be exercised in selecting the solder paste. The metal purity should be as high as practical. The flux (in the paste) must be active enough to remove the oxides formed on the metallization prior to the exposure to soldering heat. In practice this can be aided by extending the solder preheat time at temperatures below the liquidous state of the solder.
- 7.2 **Soldering:** Capacitors can be attached by conventional soldering techniques; vapor phase, convection reflow, infrared reflow, wave soldering and hot plate methods. The Soldering Profile charts show recommended time/temperature conditions for soldering. Preheating is recommended. The recommended maximum ramp rate is 2 °C per second. Attachment with a soldering iron is not recommended due to the difficulty of controlling temperature and time at temperature. The soldering iron must never come in contact with the capacitor.
- 7.2.1 Backward and Forward Compatibility: Capacitors with SnPb or 100 % tin termination finishes can be soldered using SnPb or lead (Pb)-free soldering processes.
- 8. Cleaning (Flux Removal) After Soldering: Molded capacitors are compatible with all commonly used solvents such as TES, TMS, Prelete, Chlorethane, Terpene and aqueous cleaning media. However, CFC/ODS products are not used in the production of these devices and are not recommended. Solvents containing methylene chloride or other epoxy solvents should be avoided since these will attack the epoxy encapsulation material.
- 8.1 When using ultrasonic cleaning, the board may resonate if the output power is too high. This vibration can cause cracking or a decrease in the adherence of the termination. DO NOT EXCEED 9W/I at 40 kHz for 2 minutes.
- 9. Recommended Mounting Pad Geometries: Proper mounting pad geometries are essential for successful solder connections. These dimensions are highly process sensitive and should be designed to minimize component rework due to unacceptable solder joints. The dimensional configurations shown are the recommended pad geometries for both wave and reflow soldering techniques. These dimensions are intended to be a starting point for circuit board designers and may be fine tuned if necessary based upon the peculiarities of the soldering process and/or circuit board design.

Legal Disclaimer Notice



Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk and agree to fully indemnify and hold Vishay and its distributors harmless from and against any and all claims, liabilities, expenses and damages arising or resulting in connection with such use or sale, including attorneys fees, even if such claim alleges that Vishay or its distributor was negligent regarding the design or manufacture of the part. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Document Number: 91000 www.vishay.com
Revision: 11-Mar-11 1